

Di Jiang

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/10916644/publications.pdf>

Version: 2024-02-01

14
papers

248
citations

1162889

8
h-index

1372474

10
g-index

14
all docs

14
docs citations

14
times ranked

336
citing authors

#	ARTICLE	IF	CITATIONS
1	Through-Silicon Vias Filled With Densified and Transferred Carbon Nanotube Forests. IEEE Electron Device Letters, 2012, 33, 420-422.	2.2	67
2	Vertically Stacked Carbon Nanotube-Based Interconnects for Through Silicon Via Application. IEEE Electron Device Letters, 2015, 36, 499-501.	2.2	44
3	Paper-mediated controlled densification and low temperature transfer of carbon nanotube forests for electronic interconnect application. Microelectronic Engineering, 2013, 103, 177-180.	1.1	30
4	Carbon nanotubes for electronics manufacturing and packaging: from growth to integration. Advances in Manufacturing, 2013, 1, 13-27.	3.2	22
5	Tape-Assisted Transfer of Carbon Nanotube Bundles for Through-Silicon-Via Applications. Journal of Electronic Materials, 2015, 44, 2898-2907.	1.0	21
6	Flexible Multifunctionalized Carbon Nanotubes-Based Hybrid Nanowires. Advanced Functional Materials, 2015, 25, 4135-4143.	7.8	20
7	Formation of three-dimensional carbon nanotube structures by controllable vapor densification. Materials Letters, 2012, 78, 184-187.	1.3	17
8	Embedded Fin-Like Metal/CNT Hybrid Structures for Flexible and Transparent Conductors. Small, 2016, 12, 1521-1526.	5.2	15
9	A flexible and stackable 3D interconnect system using growth-engineered carbon nanotube scaffolds. Flexible and Printed Electronics, 2017, 2, 025003.	1.5	6
10	Effect of substrates and underlayer on CNT synthesis by plasma enhanced CVD. Advances in Manufacturing, 2013, 1, 236-240.	3.2	2
11	Reliability of carbon nanotube bumps for chip on glass application. , 2014, , .		2
12	Chemically vapor deposited carbon nanotubes for vertical electronics interconnect in packaging applications. , 2014, , .		2
13	Reliability of carbon nanotube bumps for chip on film application. , 2013, , .		0
14	Carbon nanotube/solder hybrid structure for interconnect applications. , 2014, , .		0